

**SELECTIVE TREATMENT OF THE SURFACE OF A
MICROELECTRONIC WORKPIECE**

Abstract of the Disclosure

5 This invention provides a process for treating a workpiece having a front side,
a back side, and an outer perimeter. In accordance with the process, a processing
fluid is selectively applied or excluded from an outer peripheral margin of at least
one of the front or back sides or the workpiece. Exclusion and/or application of the
processing fluid occurs by applying one or more processing fluids to the workpiece
as the workpiece and corresponding reactor are spinning about an axis of rotation that
10 is generally orthogonal to the center of the face of the workpiece being processed.
The flow rate of the one or more processing fluids, fluid pressure, and/or spin rate are
used to control the extent to which the processing fluid is selectively applied or
excluded from the outer peripheral margin.